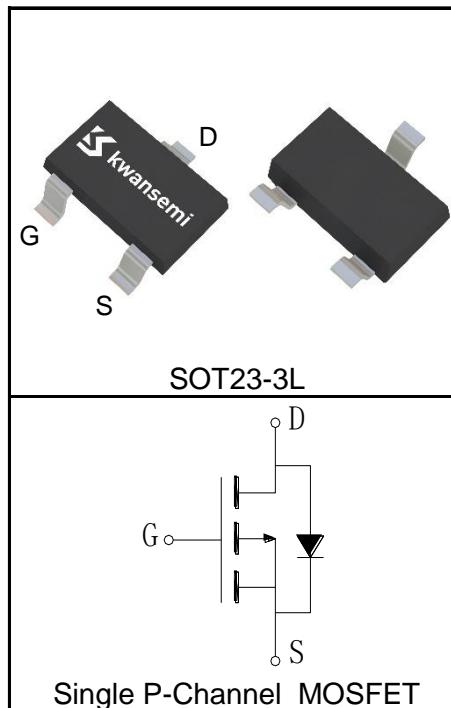


Features

- -16V/-7A,
- $R_{DS(ON)} = 13\text{m}\Omega(\text{Typ.}) @ V_{GS} = -4.5\text{V}$
- $R_{DS(ON)} = 17\text{m}\Omega(\text{Typ.}) @ V_{GS} = -2.5\text{V}$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

Pin Description



Applications

- Load Switch
- PWM Applications



Halogen-Free

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	-16	V
V_{GSS}	Gate-Source Voltage	± 12	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
I_S	Diode Continuous Forward Current	$T_A = 25^\circ\text{C}$	-1.2
Mounted on Large Heat Sink			
$I_{DP}^{(1)}$	300 μs Pulse Drain Current Tested	$T_A = 25^\circ\text{C}$	-28
$I_D^{(2)}$	Continuous Drain Current ($V_{GS} = -4.5\text{V}$)	$T_A = 25^\circ\text{C}$	-7
		$T_A = 70^\circ\text{C}$	-5.6
P_D	Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	1.25
		$T_A = 70^\circ\text{C}$	0.8
R_{qJL}	Thermal Resistance-Junction to Lead	60	$^\circ\text{C}/\text{W}$
$R_{qJA}^{(3)}$	Thermal Resistance-Junction to Ambient	100	$^\circ\text{C}/\text{W}$
Drain-Source Avalanche Ratings			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	TBD	mJ

Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

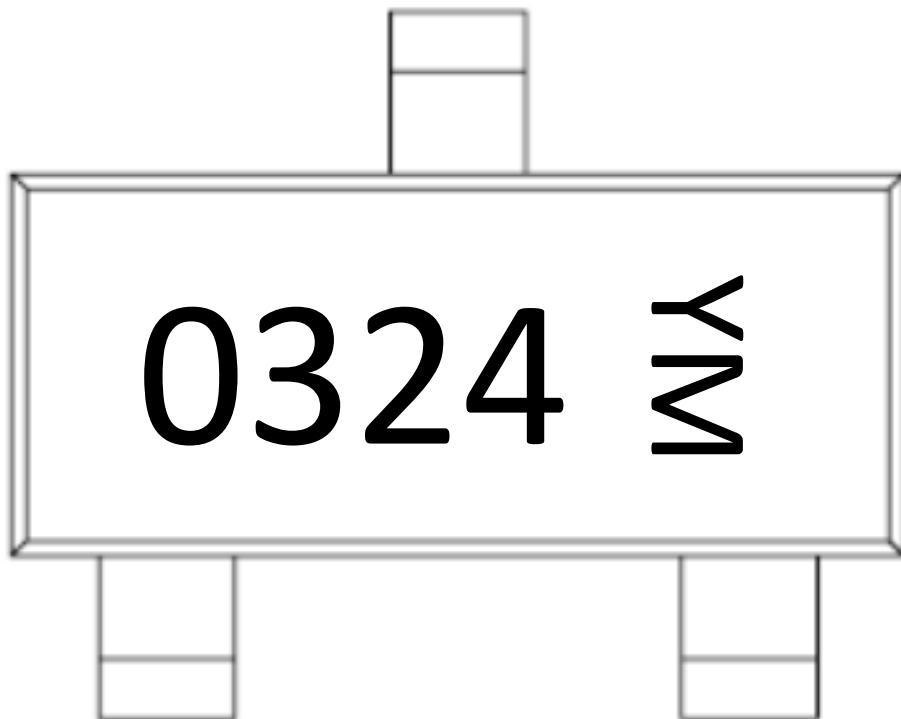
Symbol	Parameter	Test Condition	KS0324EA			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-16	-18		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-12V, V _{GS} =0V			-1	μA
		T _J =125°C			-100	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-0.4	-0.7	-1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
R _{DS(ON)} ^⑤	Drain-Source On-state Resistance	V _{GS} =-4.5V, I _{DS} =-6A		13	17	mΩ
		V _{GS} =-2.5V, I _{DS} =-5A		17	23	mΩ
Diode Characteristics						
V _{SD} ^⑤	Diode Forward Voltage	I _{SD} =-6A, V _{GS} =0V		-0.87	-1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =-6A, dI _{SD} /dt=-100A/μs		13		ns
Q _{rr}	Reverse Recovery Charge			21		nC
Dynamic Characteristics ^⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		8		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-8V, Frequency=1.0MHz		1050		pF
C _{oss}	Output Capacitance			170		
C _{rss}	Reverse Transfer Capacitance			105		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-8V, I _{DS} =-6A, V _{GEN} =-4.5V, R _G =6Ω		13		ns
t _r	Turn-on Rise Time			27		
t _{d(OFF)}	Turn-off Delay Time			38		
t _f	Turn-off Fall Time			12		
Gate Charge Characteristics ^⑥						
Q _g	Total Gate Charge	V _{DS} =-8V, V _{GS} =-4.5V, I _{DS} =-6A		18		nC
Q _{gs}	Gate-Source Charge			4.1		
Q _{gd}	Gate-Drain Charge			5.3		

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 6.5A.
- ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
- ④Limited by T_{Jmax}. Starting T_J = 25°C.
- ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

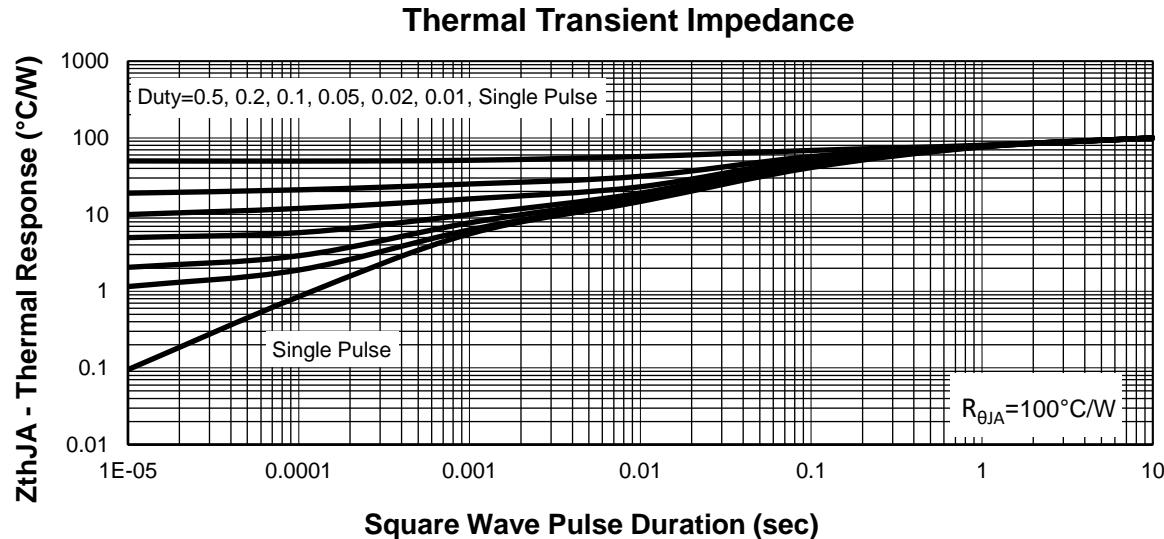
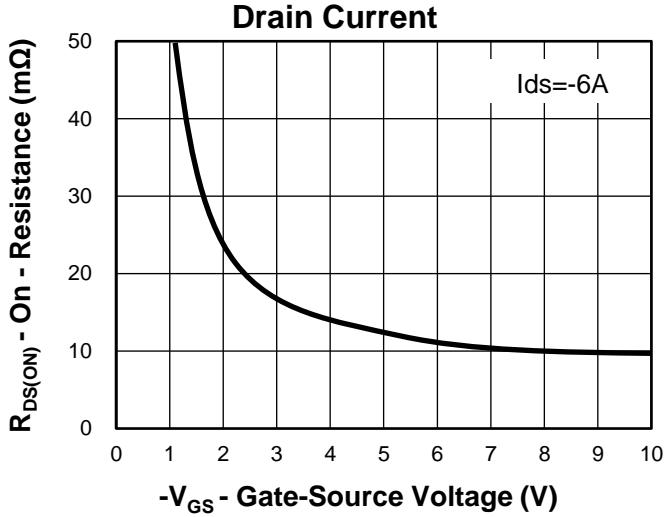
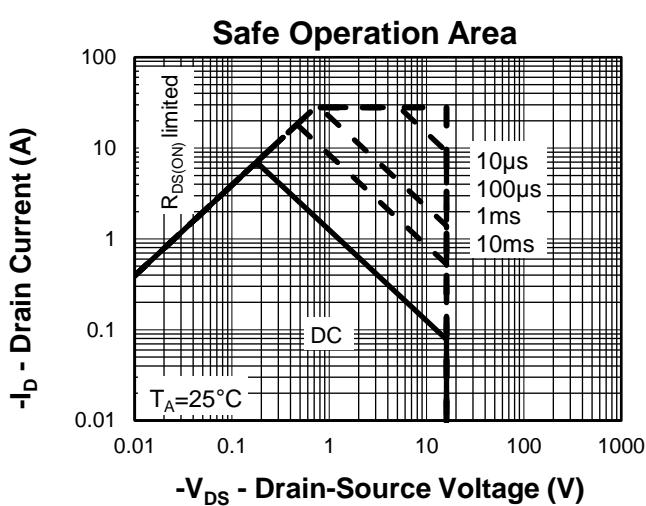
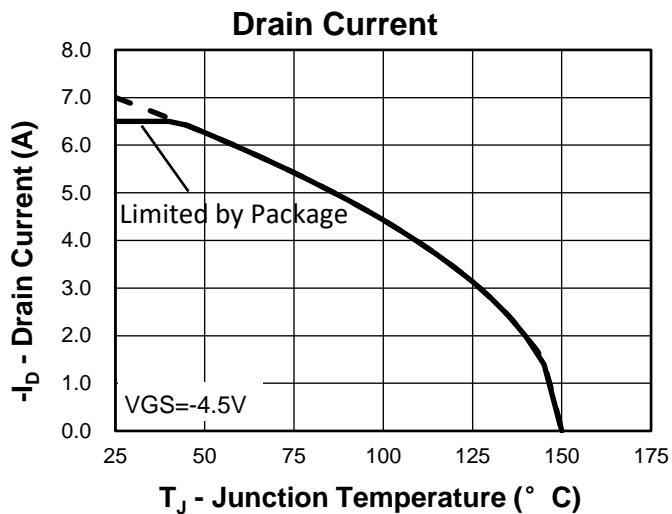
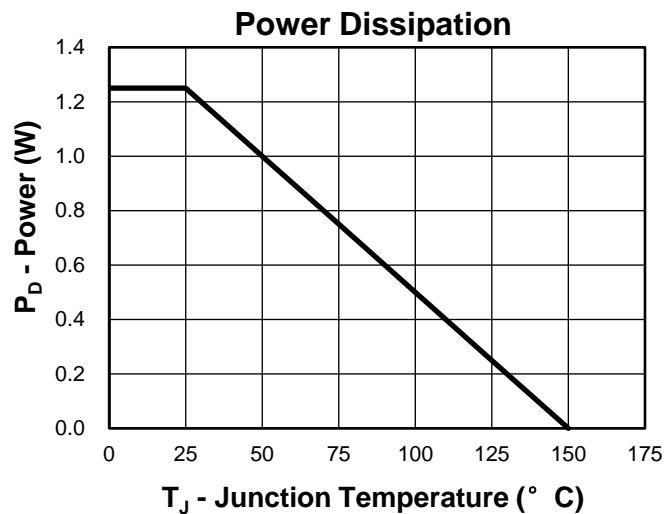
Device	Package	Packaging	Quantity	Reel Size	Tape width
KS0324EA	SOT23-3L	Tape&Reel	3000	7"	8mm



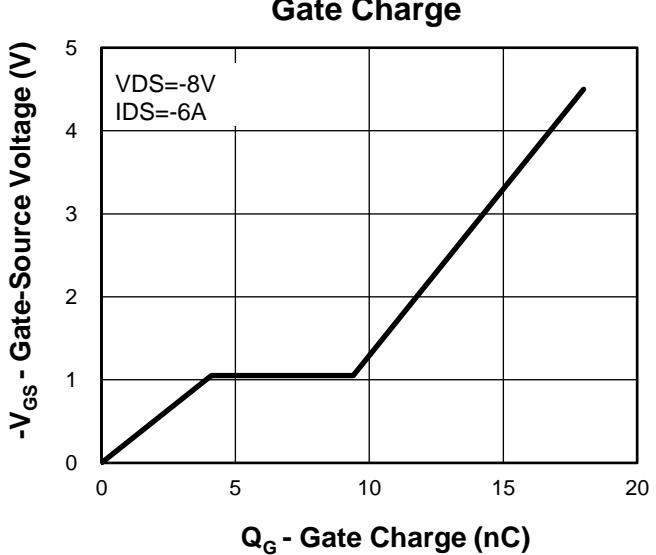
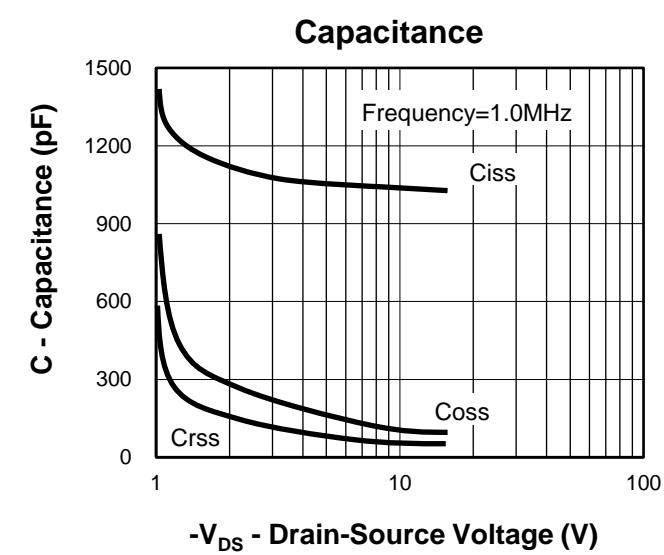
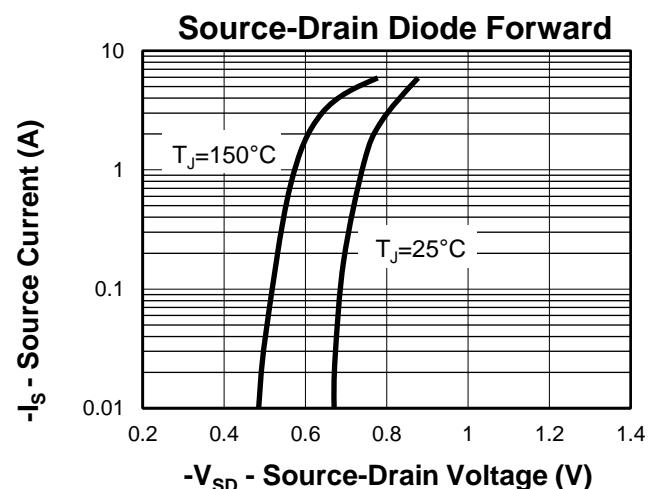
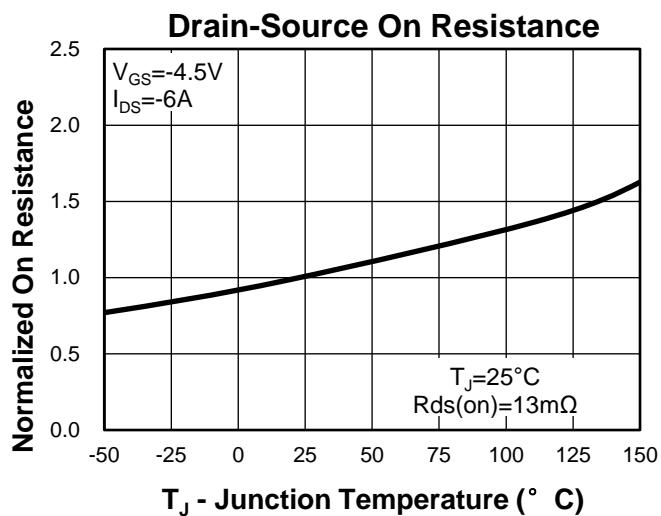
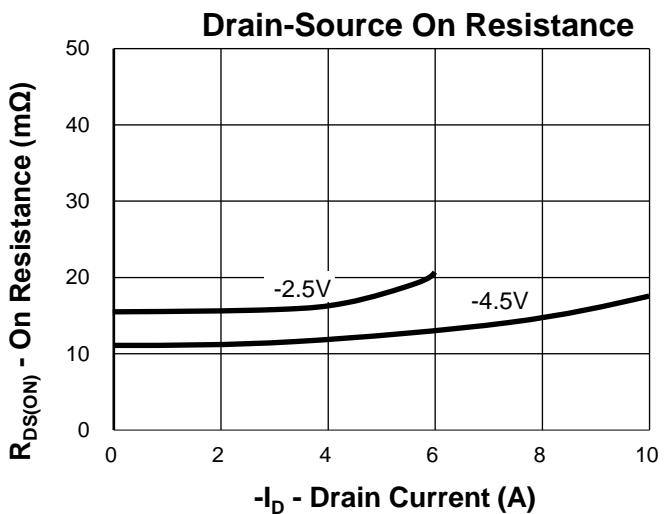
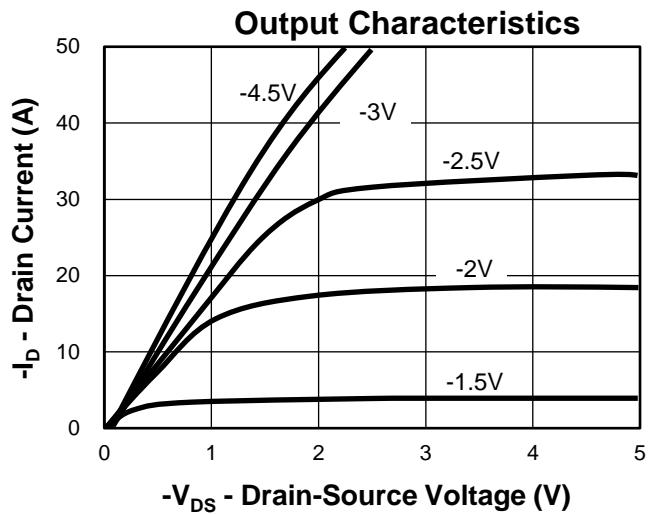
Y =Year,2017-A,2018-B,etc.

M =Month,Jan-1,Feb-2,...,Sep-9,Oct-A,Nov-B,Dec-C.

Typical Characteristics

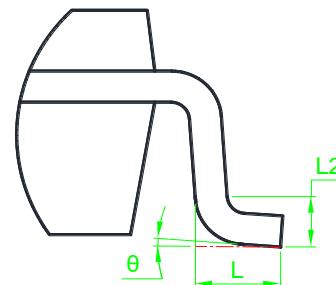
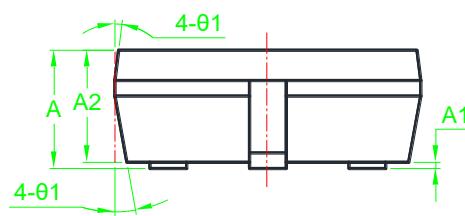
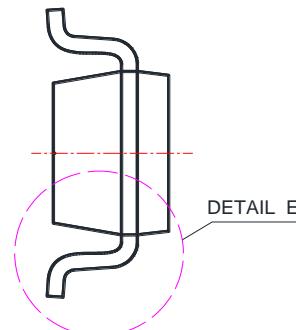
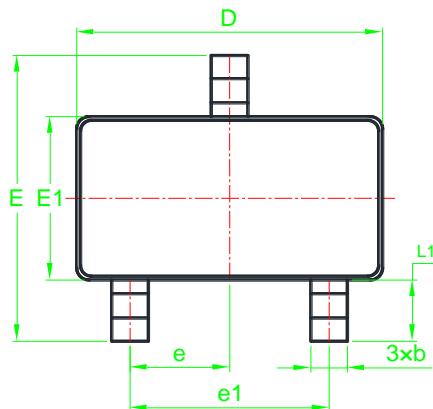


Typical Characteristics



Package Information

SOT23-3L

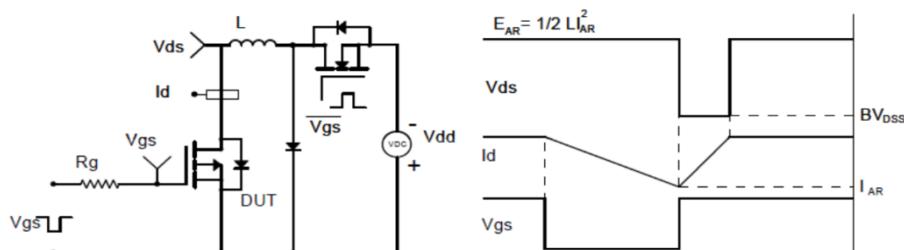


DETAIL E

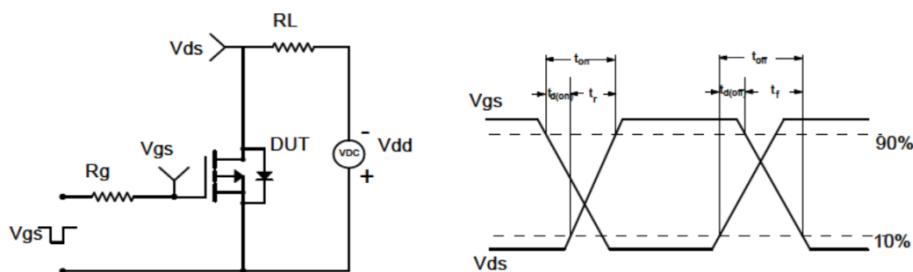
SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	1.05	1.15	1.25	0.041	0.045	0.049	e	0.95BSC			0.037BSC		
A1	0.01	*	0.10	0.000	*	0.004	e1	1.9BSC			0.075BSC		
A2	1.05	1.10	1.15	0.041	0.043	0.045	L	0.30	0.45	0.60	0.012	0.018	0.024
b	0.30	0.40	0.50	0.012	0.016	0.020	L1	0.6REF			0.024REF		
D	2.82	2.92	3.02	0.111	0.115	0.119	L2	0.254BSC			0.01BSC		
E	2.65	2.80	2.95	0.104	0.110	0.116	θ	0°	*	8°	0°	*	8°
E1	1.50	1.60	1.70	0.059	0.063	0.067	θ_1	0°	*	10°	0°	*	10°

Note: Dimensions do not include burrs and mold flash.

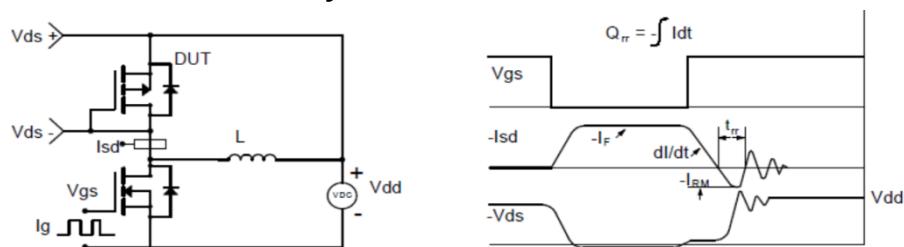
Avalanche Test Circuit and Waveforms



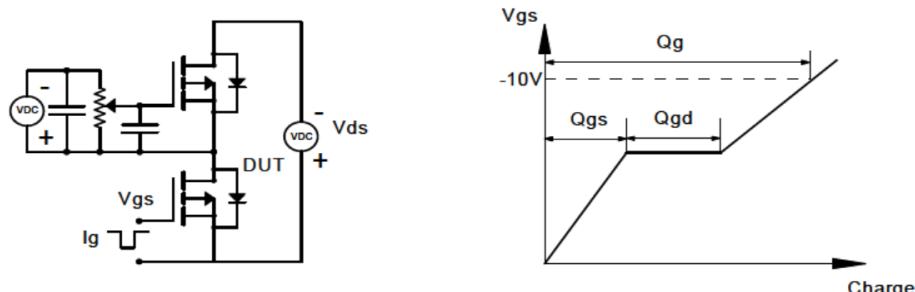
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

Kwansemi Semiconductor Co.,Ltd

Email:Sales@kwansemi.com

Web:www.kwansemi.com

DISCLAIMER:

Kwansemi reserves the right to change the specifications and circuitry without notice at any time. The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.